



2826  
PATENT APPLICATION  
Attorney Docket No. 9903-045

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Sang-Ho Ahn, et al.

Serial No. 10/008,704

Examiner: Tran, Tan N

Filed: December 6, 2001

Group Art Unit: 2826

For: ULTRA-THIN SEMICONDUCTOR PACKAGE DEVICE AND  
METHOD FOR MANUFACTURING THE SAME

TRANSMITTAL LETTER

Assistant Commissioner for Patents  
Washington, D.C. 20231

Enclosed for filing in the above-referenced application are the following:

Response to Restriction Requirement and Amendment to Specification  
 Return Post Card



20575

PATENT TRADEMARK OFFICE

Respectfully submitted,

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ON 8-5-02



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Washington, D.C. 20231

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**RESPONSE TO RESTRICTION REQUIREMENT AND AMENDMENT TO THE  
SPECIFICATION**

Responsive to the Restriction Requirement, dated July 15, 2002, Applicant hereby  
elects Group I (claims 1-29 and 50-53), without traverse.

IN THE SPECIFICATION

On page 1, line 18-21, please replace the paragraph as follows:

*a)* Fig. 1 is a cross-sectional view of a conventional IC device in which semiconductor  
chips are mounted on both sides of a lead frame in order to improve a mounting density of the  
package. This package structure is disclosed, for instance, in Japanese Utility Model  
Publication No. 62-147360.